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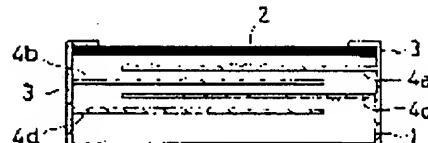
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(54) COMPOSITE ELECTRONIC COMPONENT

(57)Abstract:

PURPOSE: To manufacture a composite electronic component as one chip component and to simply connect in parallel by providing electrodes for connecting ends of both by integrally laminating a semiconductor element having positive resistance temperature coefficient with a resistor and connecting electrodes led from the element to both ends of the resistor.



CONSTITUTION: Semiconductor elements having inner electrodes 4 are, for example, press-bonded, and baked at 1300°C. Then, in order to form a fixed resistor 2, the upper surface of the uppermost semiconductor element is coated with resistance paste which mainly contains RuO₂, and seized. Inner electrodes 4 are completed by pressure pouring metal solution having a low melting point for obtaining an ohmic contact to a degassed porous layer to manufacture a positive temperature coefficient thermistor 1. Outer electrode 3 for electrically connecting the electrodes 4 exposed at both ends to the resistor 2 is provided at the thermistor 1 to obtain a composite electronic component.

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